

L Number	Hits	Search Text	DB	Time stamp
1	824	425/123.cccls. 425/89.cccls.	USPAT	2003/09/24 12:19
2	325	425/125.cccls.	USPAT	2003/09/24 12:20
3	291	425/125.cccls. not (425/123.cccls. 425/89.cccls.)	USPAT	2003/09/24 12:20
4	199	425/121.cccls.	USPAT	2003/09/24 12:46
5	156	425/121.cccls. not (425/125.cccls. (425/123.cccls. 425/89.cccls.))	USPAT	2003/09/24 13:23
6	212	425/544.cccls.	USPAT	2003/09/24 13:02
7	168	425/544.cccls. not (425/121.cccls. (425/123.cccls. 425/89.cccls.) 425/125.cccls.)	USPAT	2003/09/24 13:03
8	852	425/577.cccls.	USPAT	2003/09/24 13:23
9	809	425/577.cccls. not (425/544.cccls. 425/121.cccls. (425/123.cccls. 425/89.cccls.) 425/125.cccls.)	USPAT	2003/09/24 13:57
10	11	("2845668" "3646185" "3970734" "4025269" "4209160" "4298566" "4315520" "4647419" "4969811" "5007822" "5038455").PN.	USPAT	2003/09/24 13:39
11	4	("3136831" "3587156" "3608046" "4187272").PN.	USPAT	2003/09/24 13:40
12	5	4298566.URPN.	USPAT	2003/09/24 13:41
13	807	425/129.1.cccls.	USPAT	2003/09/24 13:57
14	546	425/129.1.cccls. not (425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)	USPAT	2003/09/24 14:21
15	4	("4244491" "4893725" "5049336" "5395005").PN.	USPAT	2003/09/24 14:03
16	524	425/127.cccls.	USPAT	2003/09/24 14:22
17	281	425/127.cccls. not (425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)	USPAT	2003/09/24 14:28
18	595	264/316.cccls.	USPAT	2003/09/24 14:29
19	176	264/272.14.cccls.	USPAT	2003/09/24 14:29
20	150	264/272.14.cccls. not (425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)	USPAT	2003/09/24 14:33
21	563	264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)	USPAT	2003/09/24 14:33
22	346573	semiconductor (semi adj conductor) encapsulation encapsulating encapsulate	USPAT	2003/09/24 14:33
23	5	(264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)	USPAT	2003/09/24 14:34

24	558	(264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) not ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.17.cccls.	USPAT	2003/09/24 14:40
25	692	264/272.17.cccls.	USPAT	2003/09/24 14:40
26	488	264/272.17.cccls. not ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.) (release parting) near5 (film sheet layer)	USPAT	2003/09/24 14:43
27	34760	(264/272.17.cccls. not ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and ((release parting) near5 (film sheet layer))	USPAT	2003/09/24 14:46
28	21	(264/272.17.cccls. not ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and ((release parting) near5 (film sheet layer))	USPAT	2003/09/24 14:41
29	4276	264/272.17.cccls. ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)	USPAT	2003/09/24 14:43

30	338	438/112.cccls.	USPAT	2003/09/24 14:43
31	305	438/112.cccls. not (264/272.17.cccls. ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/272.17.cccls. not ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and ((release parting) near5 (film sheet layer))) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.))	USPAT	2003/09/24 14:43
32	3809	(((264/272.17.cccls. not ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and ((release parting) near5 (film sheet layer))) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.))	USPAT	2003/09/24 14:44

33	333	438/112.cccls. not (((264/272.17.cccls. not ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) ((264/316.cccls. not (264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.cccls. 425/127.cccls. 425/129.1.cccls. 425/577.cccls. 425/544.cccls. (425/123.cccls. 425/89.cccls.) 425/121.cccls. 425/125.cccls.))	USPAT	2003/09/24 14:44
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34	6	(438/112.ccls. not (((264/272.17.ccls. not ((264/316.ccls. not (264/272.14.ccls. 425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)) ((264/316.ccls. not (264/272.14.ccls. 425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.ccls. 425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)) and ((release parting) near5 (film sheet layer))) ((264/316.ccls. not (264/272.14.ccls. 425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)) ((264/316.ccls. not (264/272.14.ccls. 425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)) and (semiconductor (semi adj conductor) encapsulation encapsulating encapsulate)) 264/272.14.ccls. 425/127.ccls. 425/129.1.ccls. 425/577.ccls. 425/544.ccls. (425/123.ccls. 425/89.ccls.) 425/121.ccls. 425/125.ccls.)) and ((release parting) near5 (film sheet layer))	USPAT	2003/09/24 14:45
35	0	ho11021/56	DERWENT	2003/09/24 14:46
36	10315	H01L021/56	DERWENT	2003/09/24 14:46
37	18434	(release parting) near5 (film sheet layer)	DERWENT	2003/09/24 14:46
38	101	H01L021/56 and ((release parting) near5 (film sheet layer))	DERWENT	2003/09/24 14:46
39	1	2002-350925.NRAN.	DERWENT	2003/09/24 14:47
-	5504	miyajima	JPO; DERWENT	2003/09/24 09:28
-	1505728	f	JPO; DERWENT	2003/09/24 09:28
-	18	miyajima near2 f	JPO; DERWENT	2003/09/24 09:56
-	1	2001-074385.NRAN.	DERWENT	2003/09/24 09:30
-	1	2000-099682.NRAN.	DERWENT	2003/09/24 09:39
-	1	1999-407295.NRAN.	DERWENT	2003/09/24 09:41
-	1	2001-074385.NRAN.	DERWENT	2003/09/24 09:51
-	1	jp-2000277551-\$	JPO	2003/09/24 09:55
-	0	US20020015748A1	US-PGPUB	2003/09/24 09:56
-	1	US-20020015748-A1	US-PGPUB	2003/09/24 10:01
-	383	425/89.ccls.	USPAT	2003/09/24 10:12
-	443	425/123.ccls.	USPAT	2003/09/24 10:12

-	441	425/123.ccls. not 425/89.ccls.	USPAT	2003/09/24 12:46
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